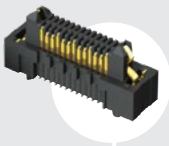
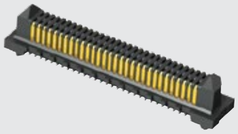
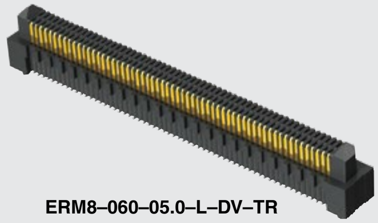
F-218 (Rev 05OCT17)

samtec

EDGE® RATE CONTACT


ERM8–013–05.0–S–DV–DS–L–TR


ERM8–030–02.0–S–DV–TR


ERM8–060–05.0–L–DV–TR

(0.80 mm) .0315"

ERM8 SERIES

RUGGED HIGH-SPEED HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?ERM8

Insulator Material:
Black LCP
Terminal Material:
Phosphor Bronze
Plating:
Au or Sn over
50 µ" (1.27 µm) Ni
Current Rating:
2.2 A per per pin
(2 pins powered)
Operating Temp Range:
-55 °C to +125 °C
Voltage Rating:
225 VAC / 318 VDC
RoHS Compliant:
Yes

PROCESSING

Lead–Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (005-030)
(0.12 mm) .005" max (040-060)*
(0.15 mm) .006" max (070-100)*
*(.004" stencil solutions may be available; contact IPG@samtec.com)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

PROTOCOLS

- 100 GbE
- PCI Express®

APPLICATIONS

STANDARD	POS.	PART NOs.	SERIES
NEXUS5001™.org POWER.org™	11	ASP-137968-01	ERM8-DV
	17	ASP-137972-01	ERM8-DV
ARM/HSSTP	20	ASP-130365-01	ERM8-DV
NEXUS5001™.org POWER.org™	23	ASP-130366-01	ERM8-DV
	35	ASP-135020-01	ERM8-DV

LEAD STYLE	A	B
–02.0	(1.61) .063	(5.97) .235
–05.0	(4.61) .181	(8.91) .351
–08.0	(7.61) .300	(11.91) .469
–09.0	(8.61) .339	(12.91) .508

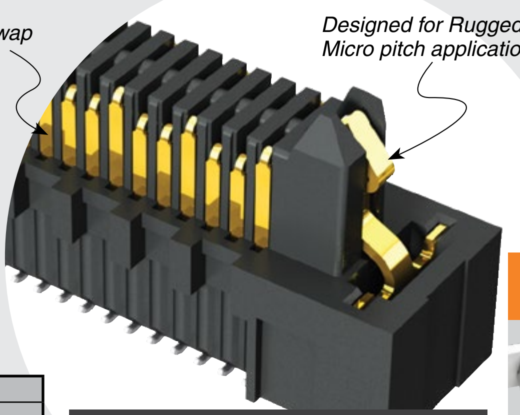
Notes:
Patented

Some lengths, styles and options are non-standard, non-returnable.

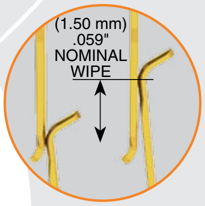
Board Mates:
ERF8

Cable Mates:
ERCD, ERDP

10 YEAR MFG WITH 30 µ" GOLD
EXTENDED LIFE PRODUCT
HIGH MATING CYCLES


Hot Swap option

Designed for Rugged Micro pitch applications



POWER/SIGNAL APPLICATION


Compatible with UMPT/UMPS for flexible two-piece power/signal solutions

ERM8 LEAD STYLE	MATED HEIGHT* ERF8 LEAD STYLE –05.0	–07.0	–09.0
–02.0	(7.00) .276	(9.00) .354	(11.00) .453
–05.0	(10.00) .394	(12.00) .472	(14.00) .551
–08.0	(13.00) .512	(15.00) .591	(17.00) .669
–09.0	(14.00) .551	(16.00) .629	(18.00) .709

*Processing conditions will affect mated height.

HIGH-SPEED CHANNEL PERFORMANCE

ERM8/ERF8 @ 7 mm Mated Stack Height

Rating based on Samtec reference channel.
For full SI performance data visit Samtec.com or contact SIG@samtec.com

PAM4
56
Gbps

ERM8 – POSITIONS PER ROW – LEAD STYLE – PLATING OPTION – DV – OTHER OPTION – TR

POSITIONS PER ROW

–005, –010, –011, –013, –020, –025, –030, –035, –040, –049, –050, –060, –070, –075,

–100
(Available with –09.0 lead style only)

LEAD STYLE

Specify LEAD STYLE from chart

PLATING OPTION

–L
= 10 µ" (0.25 µm) Gold on contact, Matte Tin on tail

–S
= 30 µ" (0.76 µm) Gold on contact, Matte Tin on tail

OTHER OPTION

–DS
= Differential Pair
(–05.0 lead style only)
(–010, –013, –025, –049 Positions only)

–K
= (4.00 mm) .157" DIA
Polyimide Film Pick & Place Pad

–L
= Latching
(–05.0 & –09.0 lead styles only)
(Not available with –EGP & –EGPS options)

–EGP
= Extended Guide Post
(–05.0 lead style only)
(Not available with –L option)

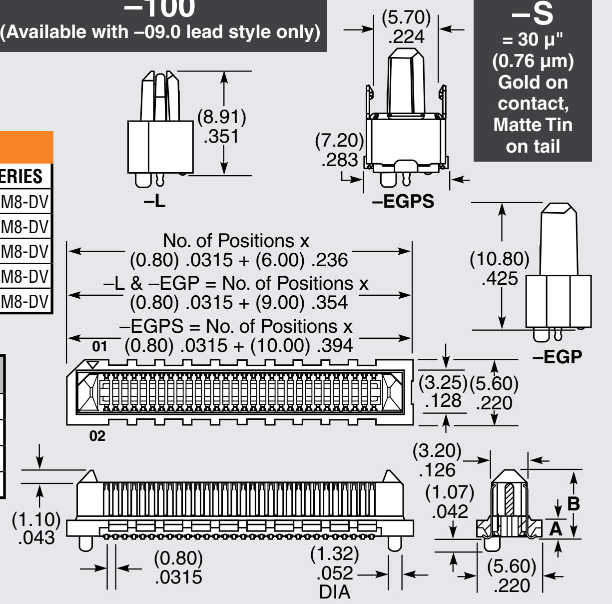
–EGPS
= Extended Guide Post Shield
(–02.0 & –05.0 lead style only)
(–010, –020, –025, –030 Positions only)
(Not available with –L option)

–DSP
= Differential Pair + Extended Guide Post
(–05.0 lead styles only)
(–013 & –025 Positions only)

–DSS
= Differential Pair + Extended Guide Post Shield
(–05.0 lead styles only)
(–025 positions only)

TR

–TR
= Tape & Reel Packaging
(Not available with 100 positions)



Due to technical progress, all designs, specifications and components are subject to change without notice.

All parts within this catalog are built to Samtec's specifications.
Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.